

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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High Temperature Silicon Carbide Power Schottky Diode

V _{RRM}	=	1200 V
V _F	=	1.6 V
I _F	=	10 A
Qc	=	95 nC

Features

- 1200 V Schottky rectifier
- 250 °C maximum operating temperature
- Electrically isolated base-plate
- Zero reverse recovery charge
- · Superior surge current capability
- Positive temperature coefficient of V_F
- Temperature independent switching behavior
- Lowest figure of merit Q_C/I_F
- Available screened to Mil-PRF-19500

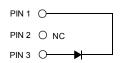
Advantages

- High temperature operation
- Improved circuit efficiency (Lower overall cost)
- · Low switching losses
- · Ease of paralleling devices without thermal runaway
- Smaller heat sink requirements
- Industry's lowest reverse recovery charge
- Industry's lowest device capacitance
- Ideal for output switching of power supplies
- Best in class reverse leakage current at operating temperature

Package

RoHS Compliant





TO - 257 (Isolated Base-plate Hermetic Package)

Applications

- Down Hole Oil Drilling, Geothermal Instrumentation
- High Temperature DC/DC Converters
- High Temperature Motor and Servo Drives
- · High Temperature Inverters
- High Temperature Actuator Control
- Military Power Supplies
- Ideal for Aerospace and Defense Applications

Maximum Ratings at T_i = 250 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak reverse voltage	V_{RRM}		1200	V
Continuous forward current	l _F	T _C ≤ 225 °C	9.4	Α
RMS forward current	I _{F(RMS)}	T _C ≤ 225 °C	16	Α
Surge non-repetitive forward current, Half Sine Wave	I _{F,SM}	T_C = 25 °C, t_P = 10 ms	45	Α
Non-repetitive peak forward current	$I_{F,max}$	T_C = 25 °C, t_P = 10 μ s	tbd	Α
l ² t value	∫i² dt	T_C = 25 °C, t_P = 10 ms	tbd	A^2S
Power dissipation	P _{tot}	T _C = 25 °C	208	W
Operating and storage temperature	T _i , T _{sta}		-55 to 250	°C

Electrical Characteristics at T_j = 250 °C, unless otherwise specified

Parameter	Symbol	Conditions -		Values		l lmi4	
				min.	typ.	max.	Unit
Diode forward voltage	V_{F}	I _F = 10 A, T _j = 25 °C		1.6		V	
Diode forward voltage	٧F	I _F = 10 A, T _j = 210 °C			2.3		V
Reverse current	I _R	V _R = 1200 V, T _j = 25 °C		1.2	20		
Reverse current		$V_R = 1200 \text{ V}, T_j =$	$V_R = 1200 \text{ V}, T_i = 250 ^{\circ}\text{C}$		56	300	μΑ
Total capacitive charge	Q _C	V _R = 400 V			58		nC
Total capacitive charge		$I_F \le I_{F,MAX}$	$V_{R} = 960 \text{ V}$		95		110
Switching time	4	dl _F /dt = 200 A/μs T _i = 210 °C	V _R = 400 V		< 49	no	
	ts	V _R = 960 V			\ 49		ns
	С	$V_R = 1 \text{ V, } f = 1 \text{ MHz, } T_j = 25 ^{\circ}\text{C}$		884			
Total capacitance		$V_R = 400 \text{ V}, f = 1 \text{ MHz}, T_j = 25 ^{\circ}\text{C}$		79		pF	
		V _R = 1000 V, f = 1 MH	lz, T _i = 25 °C		63		

Thermal Characteristics

Thermal resistance, junction - case	R_{thJC}	1.08	°C/W

Mechanical Properties

Mounting torque	M	0.6	Nm



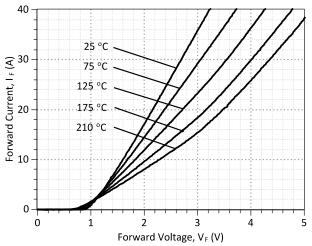


Figure 1: Typical Forward Characteristics

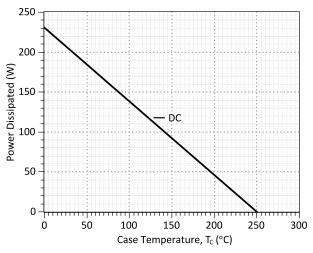


Figure 3: Power Derating Curve

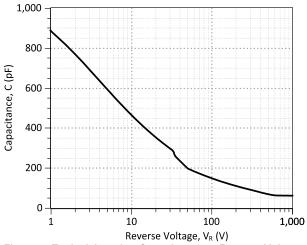


Figure 5: Typical Junction Capacitance vs Reverse Voltage Characteristics

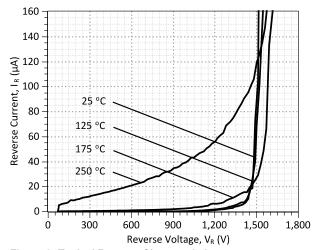


Figure 2: Typical Reverse Characteristics

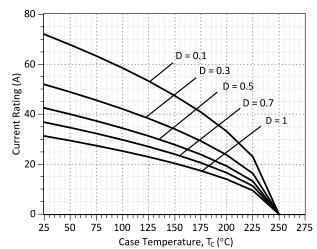


Figure 4: Current Derating Curves (D = t_P/T , t_P = 400 μ s) (Considering worst case Z_{th} conditions)

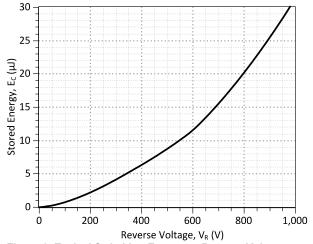


Figure 6: Typical Switching Energy vs Reverse Voltage Characteristics



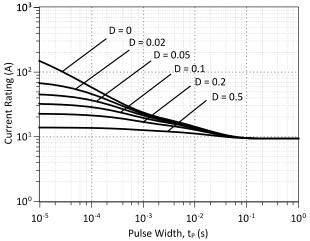


Figure 7: Current vs Pulse Duration Curves at T_c = 225 °C

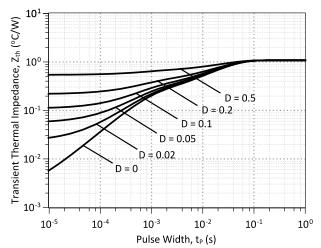
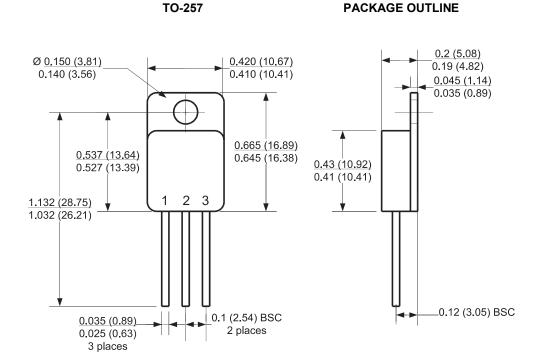


Figure 8: Transient Thermal Impedance

Package Dimensions:



- 1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
 2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS



Revision History				
Date	Revision	Comments	Supersedes	
2012/04/24	0	Initial release		

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